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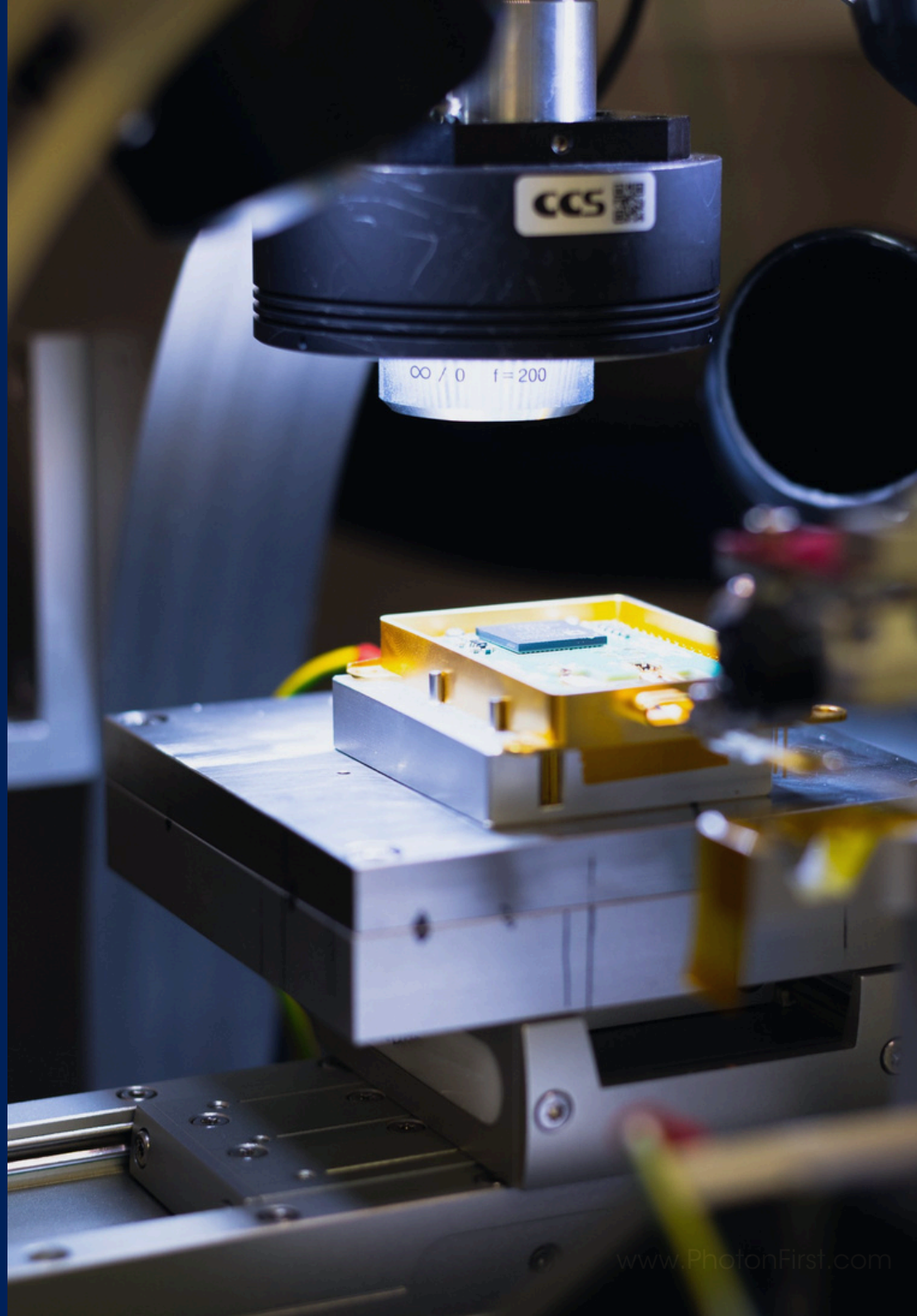
Application-specific PIC Packaging for Harsh Environments



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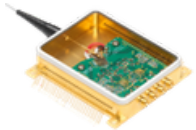
Overview of packages fit for applications

- Fibre arrays available up to 148 channels
- All packages include TEC/NTC
- Fibre options: Lensed, UHNA, PMF, SMF

	GP01/02/03	GB01	SIP01	BP01	XE01	CU01..x*
						
Highlights	Design for flexibility	High speed (4xRF)	Opto-electric, multi - chip integration	Standard form factor	Harsh Environments	Custom design for high volumes
Key features	Fast, affordable prototyping	TelCo standard package	Active-passive integration + PCBa	Quick delivery, single die	OEM-ready, system in a package	OEM-ready, mature product
Dimensions (mm)	83 × 66	53 × 55	55 × 60	39 × 35	30 × 45	40 × 50*
Fibre coupling	Edge, Array, VGC	Edge, Array	Edge, Array, VGC	Edge, Single	Edge, Array, VGC	Edge, Array, VGC
DC/RF	DC/RF	DC/RF	DC	DC	DC/RF	DC/RF
Max Frequency	10 GHz	26 GHz	DC	10 MHz	10 GHz	10 GHz
Lead time	Short	Mid	Mid	Short	Long	Long
Sealing	Open system	Soldering	Soldering / Epoxy	Soldering	Hermetic	Hermetic

*CU01..x series are application-specific packages. Specifications will vary depending on customer requirements.

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